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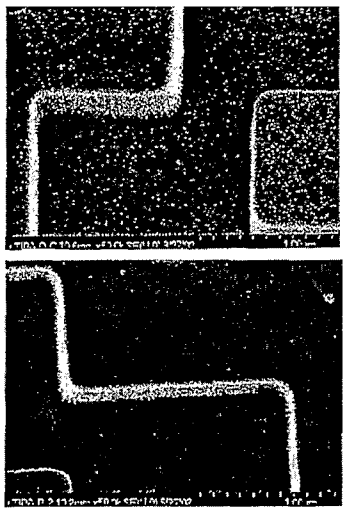
(54) Title: COMPOSITIONS AND METHODS FOR HIGH-EFFICIENCY CLEANING/POLISHING OF SEMICONDUCTOR WAFERS



(57) Abstract: A composition including supercritical fluid and at least one additive selected from fluoro species, and primary and/or secondary amines, optionally with co-solvent, low k material attack-inhibitor(s) and/or surfactant(s). The composition has particular utility for cleaning of semiconductor wafers to remove post-ashing residues therefrom.

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